IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Sun et al.

Serial No.: 10/616,097

Confirmation No.: 1645

Filed:

July 8, 2003

For:

Multiple-Step

Electrodepositon Process for Direct Copper Plating

on Barrier Materials

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Examiner: Edna Wong

Group Art Unit: 1753

MAIL STOP AMENDMENT Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 CERTIFICATE OF MAILING OR TRANSMISSION

I hereby certify that this correspondence is being deposited on with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Mail Stop Missing Parts, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, or electronically transmitted to the U.S. Patent and Trademark Office via EFS-Web to the attention of the Commissioner for Patents, on the date shown below.

September 15, 2006

Date

John-Paul F. Cherry

Dear Sir:

RESPONSE TO OFFICE ACTION DATED MAY 15, 2006

In response to the Office Action dated May 15, 2006, having a shortened statutory period for response extended by one month and set to expire on September 15, 2006, please enter this Response and reconsider the claims pending in the application for reasons discussed below. Transmitted with this Response is a Petition for Extension of Time and the authority to charge fees. Although the Applicant believes that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPM/008241/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

Amendments to the Claims begin on page 2 of this paper. Remarks begin on page 8 of this paper.